IXYS
INTEGRATED CIRCUITS DIVISION

PLA140
Single-Pole Normally Open OptoMOS® Relay

Parameter	Rating	Units
Blocking Voltage	400	V_P
Load Current	250	mA_{rms} / mA_{DC}
On-Resistance (max)	8	Ω

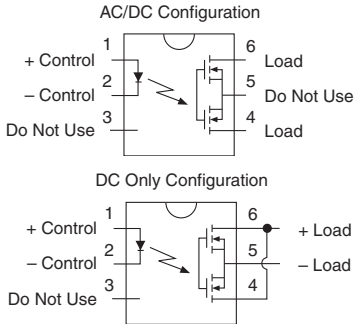
Features

- Low On-Resistance, High Current Handling
- Low Drive Power Requirements
- 3750V_{rms} Input/Output Isolation
- High Reliability
- VDE Compatible
- FCC Compatible
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Flammability Rating UL 94 V-0
- Small 6-Pin Package
- Surface Mount Tape & Reel Version Available

Applications

- Telecommunications
  - Telecomm Switching
  - Hook Switch
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls
- Automotive

Pin Configuration



Description

The PLA140 is a single-pole normally open (1-Form-A) Solid State Relay that uses optically coupled MOSFET technology to provide 3750V_{rms} of input-to-output isolation.

MOSFET output switches, which use IXYS Integrated Circuits' patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

The PLA140's combination of low on-resistance and high load current handling makes it suitable for a variety of industrial applications.

Because Solid State Relays like the PLA140 have no moving parts, they offer faster, bounce-free switching in a more compact surface mount or though hole package than traditional electromechanical relays.

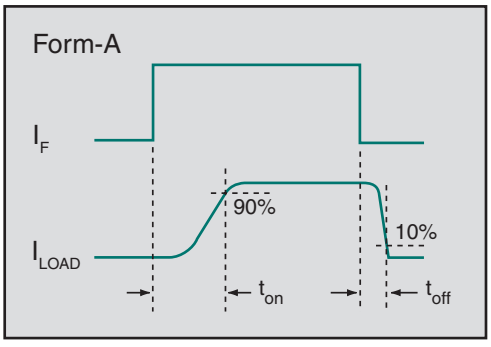
Approvals

- UL Certified Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component: Certificate available on our website

Ordering Information

Part Number	Description
PLA140	6-Pin DIP (50/Tube)
PLA140S	6-Pin Surface Mount (50/Tube)
PLA140STR	6-Pin Surface Mount (1,000/Reel)

Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25ºC

Parameter	Ratings	Units
Blocking Voltage	400	V_P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	150	mW
Total Power Dissipation [2]	800	mW
Isolation Voltage, Input to Output	3750	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33 mW / ºC
[2] Derate linearly 6.67 mW / ºC

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

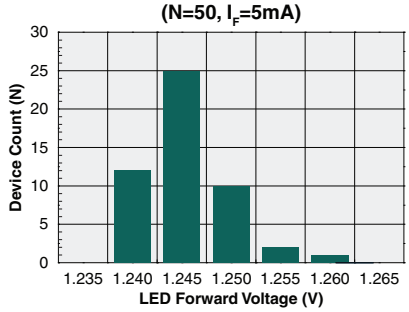
Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25ºC

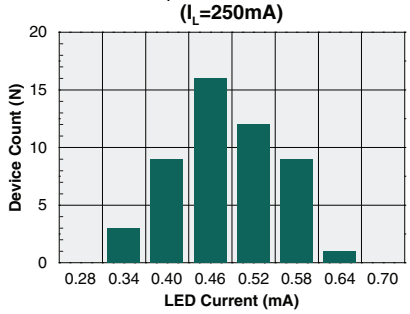
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current (Continuous)						
AC/DC Configuration	I_F=5mA	I_L	-	-	250	mA_{rms} / mA_{DC}
DC Configuration			-	-	350	mA_{DC}
Peak Load Current	I_F=5mA , t=10ms	I_{LPK}	-	-	±500	mA_P
On-Resistance						
AC/DC Configuration	I_F=5mA , I_L=250mA	R_{ON}	-	5.5	8	Ω
DC Configuration	I_F=5mA , I_L=350mA		-	1.5	3	
Off-State Leakage Current	V_L=400V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=5mA, V_L=10V	t_{on}	-	0.4	3	ms
Turn-Off		t_{off}	-	0.19	1	
Output Capacitance	I_F=0mA , V_L=50V, f=1MHz	C_{OUT}	-	18	-	pF
Input Characteristics						
Input Control Current to Activate	I_L=250mA	I_F	-	0.46	5	mA
Input Control Current to Deactivate	-	I_F	0.2	0.44	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.2	1.5	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Common Characteristics						
Input to Output Capacitance	V_{IO}=0V, f=1MHz	C_{IO}	-	3	-	pF

PERFORMANCE DATA*

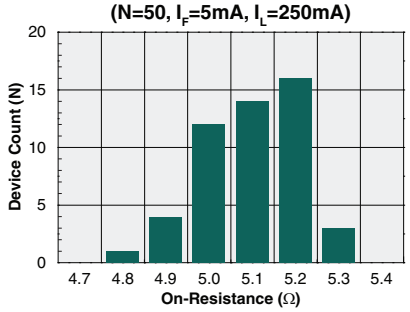
Typical LED Forward Voltage Drop (N=50, I_F=5mA)



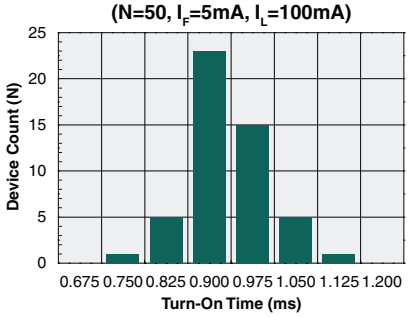
Typical I_F for Switch Operation (I_L=250mA)



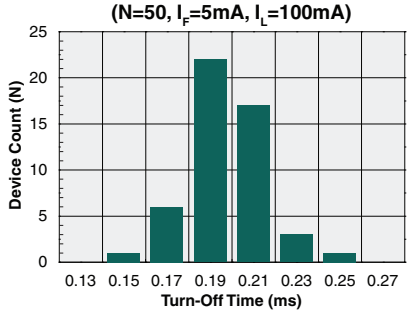
Typical On-Resistance Distribution (N=50, I_F=5mA, I_L=250mA)



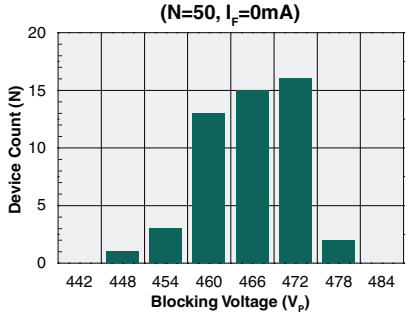
Typical Turn-On Time (N=50, I_F=5mA, I_L=100mA)



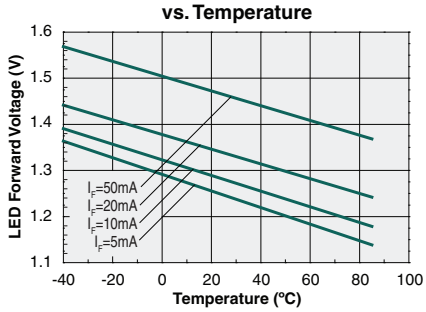
Typical Turn-Off Time (N=50, I_F=5mA, I_L=100mA)



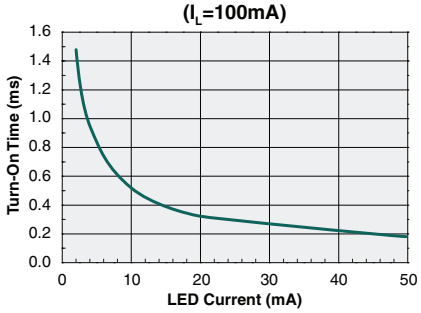
Typical Blocking Voltage Distribution (N=50, I_F=0mA)



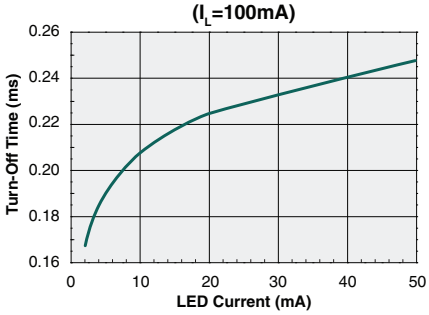
Typical LED Forward Voltage Drop vs. Temperature



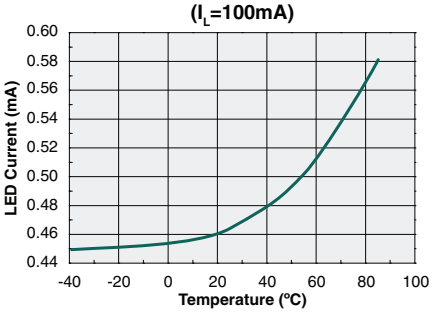
Typical Turn-On Time vs. LED Forward Current (I_L=100mA)



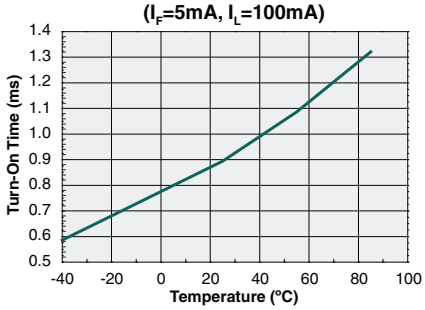
Typical Turn-Off Time vs. LED Forward Current (I_L=100mA)



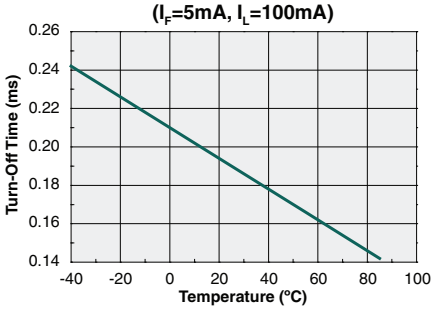
Typical I_F for Switch Operation vs. Temperature (I_L=100mA)



Typical Turn-On Time vs. Temperature (I_F=5mA, I_L=100mA)



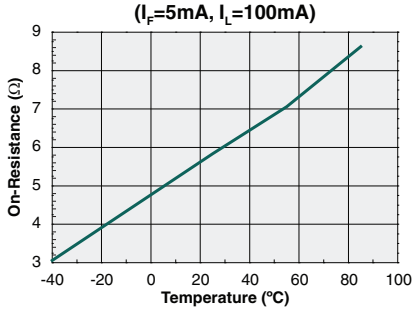
Typical Turn-Off Time vs. Temperature (I_F=5mA, I_L=100mA)



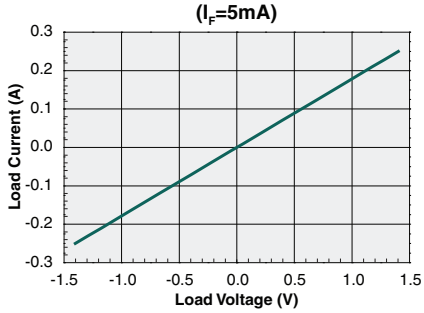
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

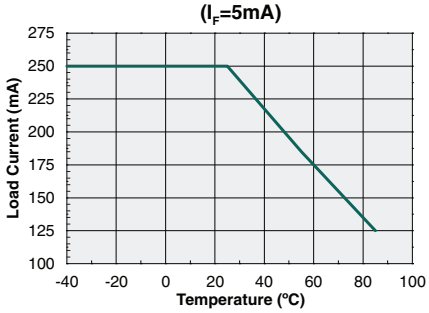
Typical On-Resistance vs. Temperature
AC/DC Configuration
(I_F=5mA, I_L=100mA)



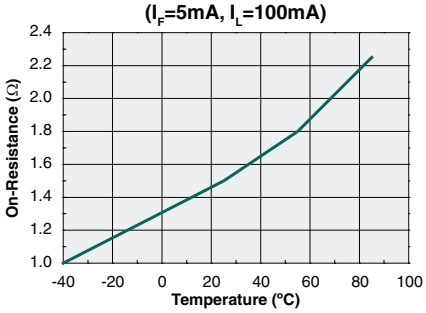
Typical Load Current vs. Load Voltage
AC/DC Configuration
(I_F=5mA)



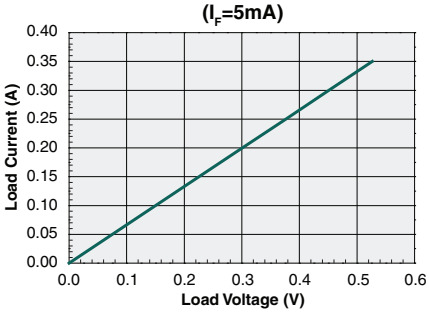
Maximum Load Current
vs. Temperature - AC/DC Configuration
(I_F=5mA)



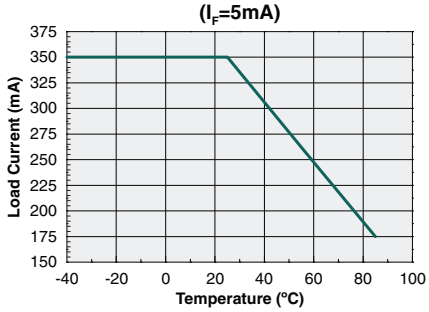
Typical On-Resistance vs. Temperature
DC-Only Configuration
(I_F=5mA, I_L=100mA)



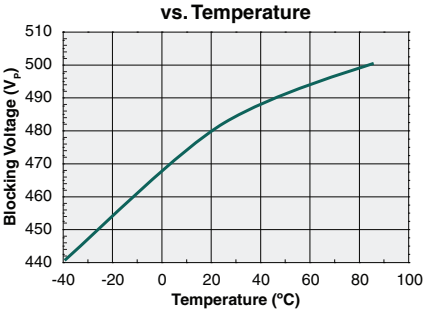
Typical Load Current vs. Load Voltage
DC-Only Configuration
(I_F=5mA)



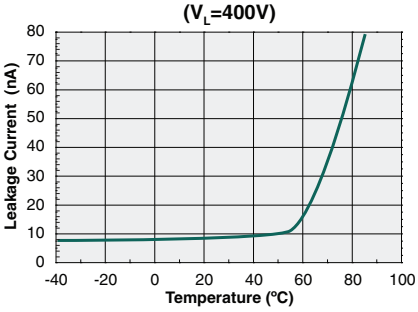
Maximum Load Current
vs. Temperature - DC-Only Configuration
(I_F=5mA)



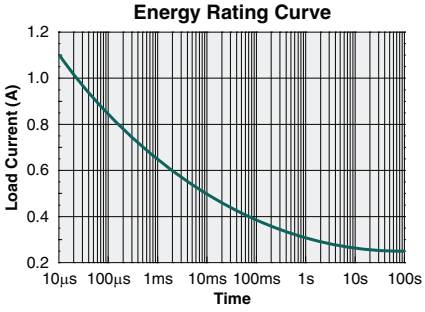
Typical Blocking Voltage
vs. Temperature



Typical Leakage vs. Temperature
Measured Across Pins 4&6
(V_L=400V)



Energy Rating Curve



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25ºC.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
PLA140 / PLA140S	MSL 1

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

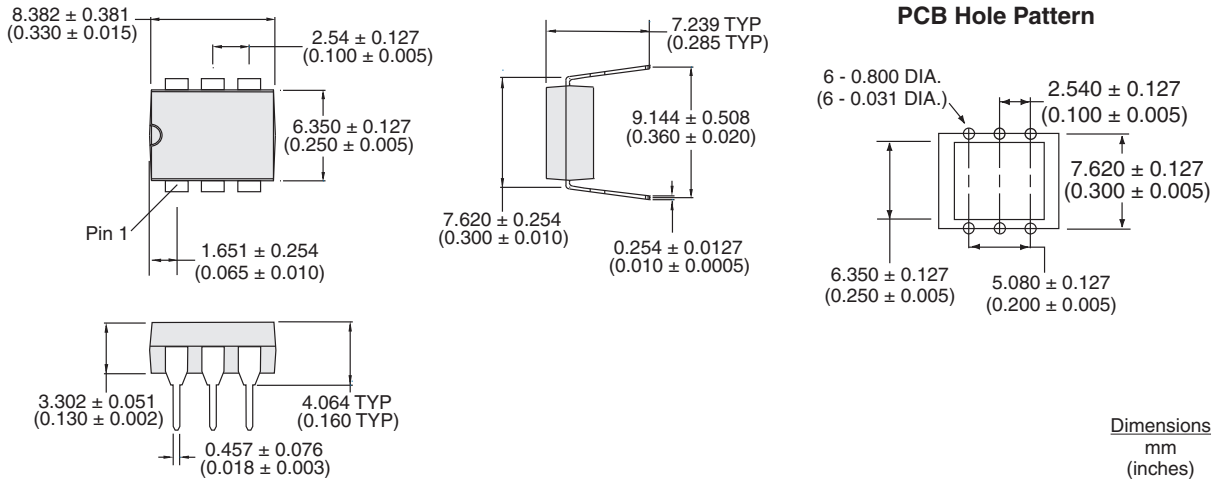
Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
PLA140	250°C	30 seconds	1
PLA140S	250°C	30 seconds	3

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

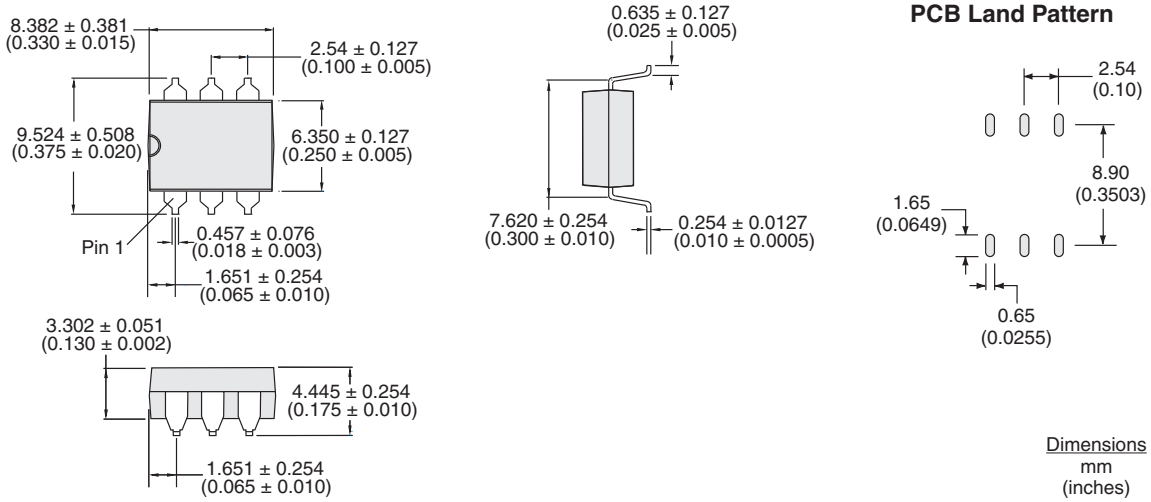
MECHANICAL DIMENSIONS

PLA140



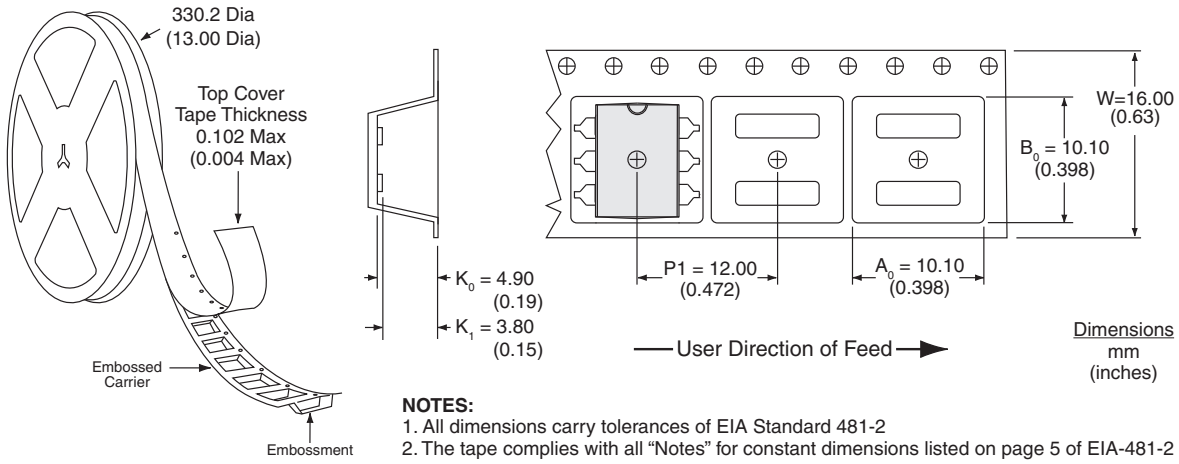
Dimensions
mm
(inches)

PLA140S



Dimensions
mm
(inches)

PLA140STR Tape & Reel



NOTES:
1. All dimensions carry tolerances of EIA Standard 481-2
2. The tape complies with all "Notes" for constant dimensions listed on page 5 of EIA-481-2

For additional information please visit our website at: www.ixysic.com

Specification: DS-PLA140-R09

6/27/2018